

Pref. the moulding contains up to 20 wt.% alkaline earth metal halide besides (A), (B), and (C). MATERIAL - Fuji Silicagel Type-A, B, RD, or AB (RTM, Fuji-Devison Corp.) is suitably used. Sawdust chips (2-3 mm) or wastepaper (5 mm) are used as (B). (C) is hydrophilic vinyl chloride, vinyl acetate, or PVA emulsion. The alkaline earth metal halide includes CaCl_2 or MgCl_2 .

USE/ADVANTAGE - Used as a construction material for drying houses or buildings. The moulding is easy to handle

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Title Terms: MOIST; ABSORB; TILE; BUILD; OBTAIN; MOULD; DRY; MIXTURE;

CONTAIN; SILICIC; ACID; GEL; FIBRE; MATERIAL; ADHESIVE

Derwent Class: A93; J01; Q43

International Patent Class (Main): B01J-020/10

International Patent Class (Additional): B01D-053/26; B01J-020/28;

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File Segment: CPI; EngPI

Manual Codes (CPI/A-N): A12-R01; J01-E01; J01-E03C

Plasdoc Codes (KS): 0209 0231 0759 0787 2007 2504 2682 2691 2694 2696 3250 3316

Polymer Fragment Codes (PF):

001 014 04- 061 062 063 066 067 231 244 245 397 436 52& 532 533 535 54& 609 613 614 616 678 688

WPI Acc No: 1994-179394/ 199422

XRPX Acc No: N94-141356

EL device with back electrode and carbon-metal conductive paste layer - provides surface opposite to back electrode insulation layer with moisture capturing layer NoAbstract

Patent Assignee: SEIKOSHA KK (SUWB)

Number of Countries: 001 Number of Patents: 001

Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Week
JP 6119970	A	19940428	JP 92264743	A	19921002	199422 B

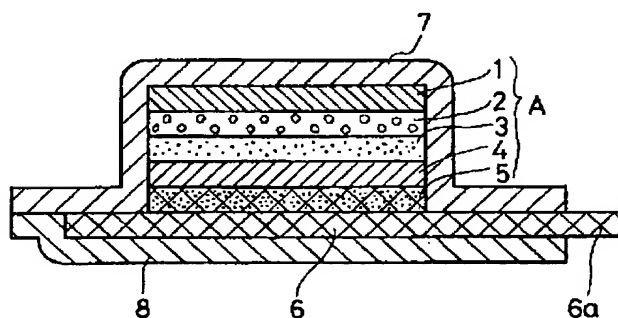
Priority Applications (No Type Date): JP 92264743 A 19921002

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Patent No	Kind	Lan	Pg	Main IPC	Filing Notes
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Abstract (Basic): JP 6119970 A

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Title Terms: ELECTROLUMINESCENT; DEVICE; BACK; ELECTRODE; CARBON; METAL;

CONDUCTING; PASTE; LAYER; SURFACE; OPPOSED; BACK; ELECTRODE; INSULATE;
LAYER; MOIST; CAPTURE; LAYER; NOABSTRACT
Index Terms/Additional Words: ELECTROLUMINESCENT
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International Patent Class (Additional): H05B-033/06
File Segment: EPI
Manual Codes (EPI/S-X): U14-J02

EL ELEMENT

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ABSTRACT

PURPOSE: To reduce the costs for works by capturing sufficiently the water/moisture intruding, protecting a light emitting layer and an insulative layer, enhance the quality of an EL element, preventing the resistance value from being uneven over the plane of a back plate, and eliminating necessity for the process of installing a drawout electrode as any separate process.

CONSTITUTION: A light emitting layer 2 is formed on a transparent conductive film 1 which is a clear electrode, and thereover an insulative layer 3 is formed, whereover a back plate 4 is formed. The back plate 4 is prepared from a conductive paste to which carbon powder or metal powder is added followed by kneading, and the resultant is subjected to printing and drying. A powder moisture absorbing substance is added to this conductive paste, and the resultant paste is printed on the back plate 4 and dried to form a conductive water capture layer 5. A lead electrode plate 6 made of a metal material is attached onto this water capture layer 5. The lead electrode plate 6 is provided with a drawout electrode rigidly, and these are led electrically to the clear electrode 1 and back plate 4, respectively, and the protruding ends are cut so as to generate insulated state. The peripheral part is sealed by hot pressure attaching while pinched by a moisture preventive film 7 and a PET film 8 from above and below.